

PRODUCT NUMBER

10056845-YXXYLF

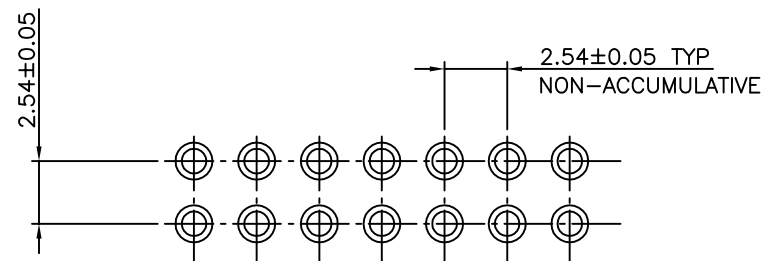
PLATING
 1- 0.76µm GOLD/GXT (PdNi WITH GOLD FLASH) ON CONTACT AREA
 2µm MIN MATTE TIN ON TAILS.
 1.27µm NICKEL MIN UNDERPLATING

LEAD FREE, RoHS COMPATIBLE, NOTE 8.
 PACKAGING NOTE 5

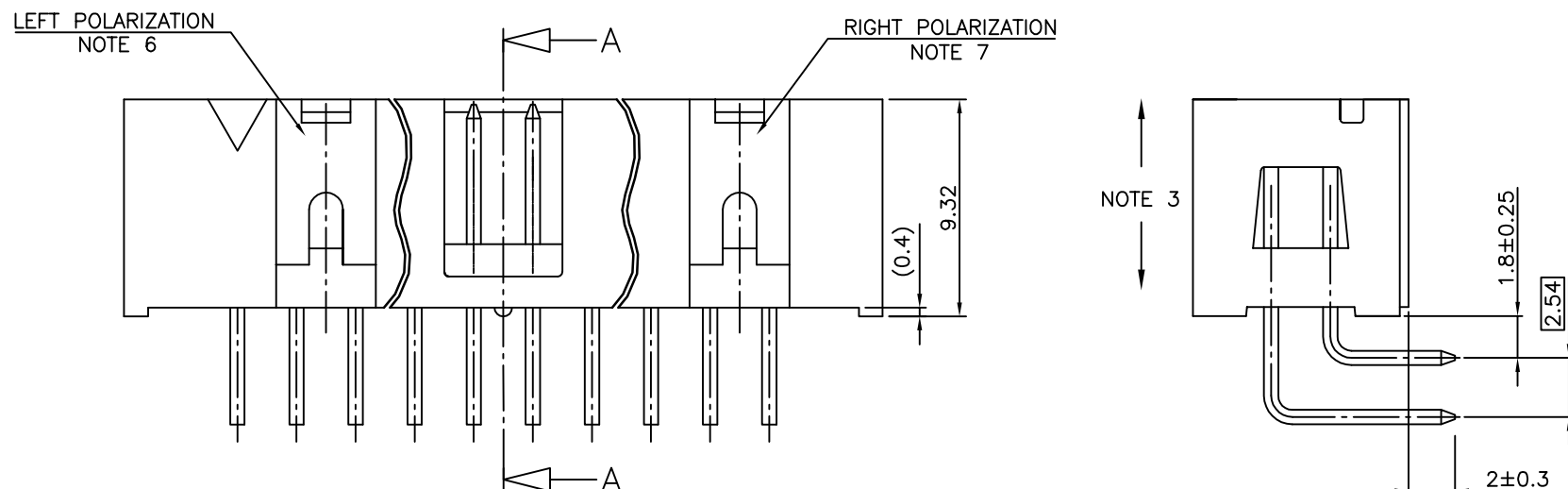
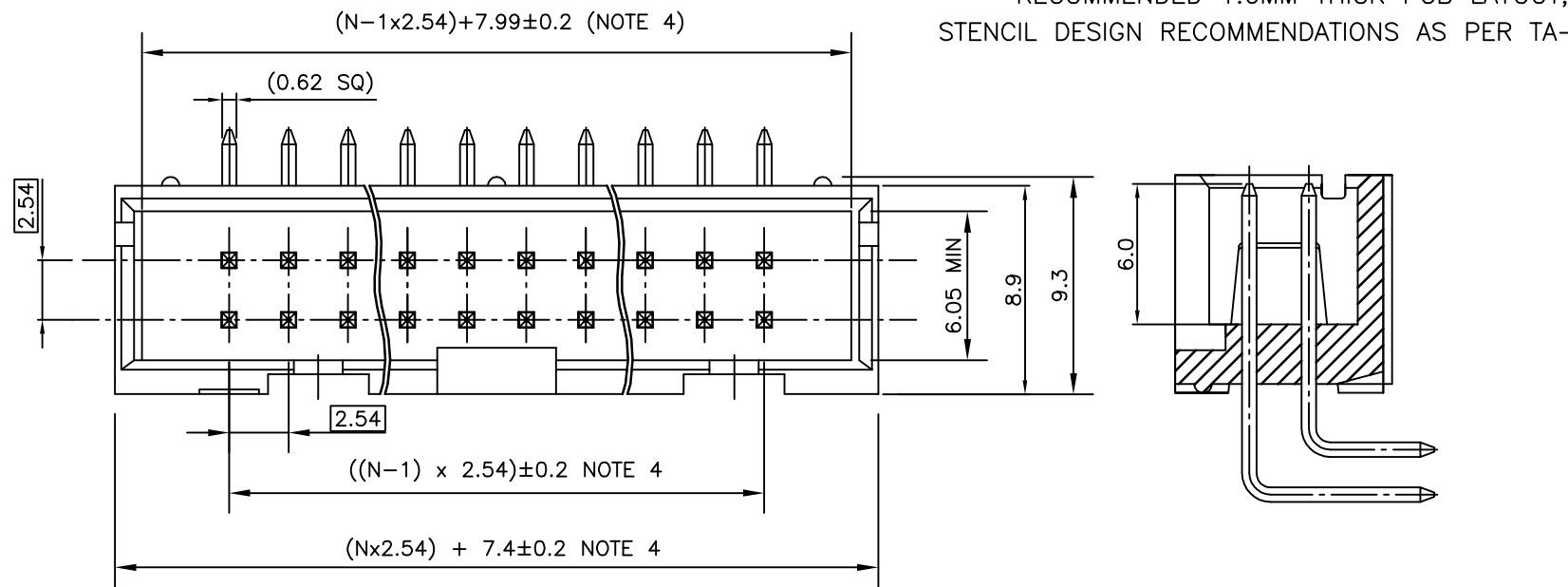
STYLE	SIZE
06	2x03
08	2x04
10	2x05
14	2x07
16	2x08
20	2x10
26	2x13
30	2x15
34	2x17
40	2x20

NOTES:

- 1 - HOUSING MATERIAL: HIGH TEMPERATURE THERMOPLASTIC, UL94 V-0 COLOR BLACK.
- 2 - CONTACT MATERIAL: COPPER ALLOY
- 3 - MINIMUM PUSH OUT FORCE OF PIN IN EITHER DIRECTION : 20N BEFORE SOLDERING.
- 4 - TO DETERMINE DIMENSIONS :
 N = NUMBER OF POSITIONS PER ROW
 EXAMPLE : 8 POS N x 2.54 = 20.32mm
- 5 - PACKAGING:
 OMMIT = STANDARD TUBE PACKAGING.
 K = TAPE AND REEL PACKAGING WITHOUT CAP ON REQUEST.
- 6 - NO LEFT POLARIZATION ON STYLE 06, 08, 10, 14.
- 7 - NO RIGHT POLARIZATION ON STYLE 06, 08.
8. RoHS COMPLIANT & COMPATIBLE PRODUCT SPECIFICATIONS
 - a - PLATING:
 - "LF" MEANS THE PRODUCT IS LEAD-FREE AND RoHS COMPLIANT
 2µm MINIMUM MATTE TIN ON TAILS OVER 1.27µm MINIMUM NICKEL UNDERPLATE.
 - b - THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS PER GS-22-008.
 - c - MANUFACTURING PROCESS COMPATIBILITY
 - THE HOUSING WILL WITHSTAND EXPOSURE TO 260° PEAK TEMPERATURE FOR 10-30 SECONDS IN A CONVECTION INFRA-RED OR VAPOR PHASE REFLOW OVEN.



RECOMMENDED 1.6MM THICK PCB LAYOUT,
 STENCIL DESIGN RECOMMENDATIONS AS PER TA-894



mat'l. code		surface		tolerance		projection		product family	
NOTES 1, 2		ISO 1302		ISO 406 ISO 1101		mm		QKIE HDR	
ltr	ecn no	dr	date	tolerances unless otherwise specified		mm		title	
A	F06-0280	LMU	06.09.19	linear		mm		QKIE HEADER	
B	F06-0335	LMU	06.12.08	linear		mm		LOW PROFILE PIN IN PASTE	
C	F07-0198	LMU	07.05.30	linear		mm		scale 1:1	
D	F08-0146	YOY	08.04.11	dr	L.MULIN	06.07.03		dwg no	
E	F12-0089	JCO	12.07.23	engr	J.COMPAGNON	06.07.03		sheet 1 of 1	
sheet index		revision sheet		chr		appd		JM.C 06.09.19	
								10056845	
								CUSTOMER Drawing	

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